



WHISTLER.
Procurement Simplified

Test/Inspection	Minimum Sample Size	
	Lot Size 200 or greater Devices	Lot Size 1-199 Devices (See NOTE 1)
Minimum Required Tests		
Documentation & Packaging		
Documentation & Packaging Inspection (4.2.6.4.1) (non destructive)	All Devices	All Devices
External Visual Inspection		
a. General (4.2.6.4.2.1) (non-destructive)	All Devices	All Devices
b. Detailed (4.2.6.4.2.2) (non-destructive)	122 Devices	122 or all devices, whichever is less
Remarking & Resurfacing (destructive)	See NOTE 2	See NOTE 2
Solvent Test for Remarking (4.2.6.4.3.A) (destructive)	3 Devices	3 Devices
Solvent Test for Remarking (4.2.6.4.3.B) (destructive)	3 Devices	3 Devices
Radiological (X-Ray) Inspection		
X-Ray Inspection (4.2.6.4.4) (non-destructive)	45 Devices	45 Devices or all devices, whichever is less
Lead Finish Evaluation (XRF or EDS/EDX)	See NOTE 3	See NOTE 3
XRF (non-destructive) or EDS/EDX (destructive) (4.2.6.4.5) (Appendix C.1)	3 Devices	3 Devices
Delid/Decapsulation Internal Analysis (destructive)	See NOTE 4	See NOTE 4
Delid/Decapsulation (4.2.6.4.6) (destructive)	3 Devices	3 Devices
Additional Tests (as agreed between Customer & Organization)		
Remarking & Resurfacing (destructive)	See NOTE 2	See NOTE 2
Scanning Electron Microscope (4.2.6.4.3 C) (destructive)	3 Devices	3 Devices
Quantative Surface Analysis (4.2.6.4.3 D) (non-destructive)	5 Devices	5 Devices
Thermal Testing		
Thermal Cycling Test (Appendix C.2)	All Devices	All Devices
Burn In		
Burn In (Pre & Post) (Appendix C.4)	45 Devices	45 Devices or all devices, whichever is less
Hermetically Verification (Fine & Gross Leak)		
Hermetically Verification (Fine & Gross Leak) (Appendix C.5)	All Devices	All Devices
Scanning Acoustic Microscopy (SAM)		
Scanning Acoustic Microscopy (SAM) Appendix C.6)	As Specified	As Specified
Other		
Other test/inspections	As Specified	As Specified



Table Notes

Documentation and Packaging A1 Documentation and Packaging Inspection (4.2.6.4.1) (non-destructive) All devices
All devices External Visual Inspection A2 a. General (4.2.6.4.2.1) (non-destructive) All devices All devices b. Detailed
(4.2.6.4.2.2) (non-destructive) 122 devices 122 or all devices, whichever is less

Remarking & Resurfacing (destructive) See NOTE 2 See NOTE 2 A3 Solvent Test for Remarking (4.2.6.4.3 A)
(destructive) 3 devices 3 devices Solvent Test for Resurfacing (4.2.6.4.3 B) (destructive) 3 devices 3 devices
Radiological (X-Ray) Inspection A4 X-Ray Inspection (4.2.6.4.4) (non-destructive) 45 devices 45 devices or all
devices, whichever is less

Lead Finish Evaluation (XRF or EDS/EDX) See NOTE 3 See NOTE 3 A5 XRF (non-destructive) or EDS/EDX
(destructive) (4.2.6.4.5) (Appendix C.1) 3 devices 3

Delid/Decapsulation Internal Analysis (destructive) See NOTE 4 See NOTE 4 A6 Delid/Decapsulation (4.2.6.4.6)
(destructive) 3 devices 3 devices Additional Tests (as agreed between Customer and Organization) Remarking
& Resurfacing (destructive) See NOTE 2 See NOTE 2 A3 Option Scanning Electron Microscope (4.2.6.4.3 C)
(destructive) 3 devices 3 devices Quantitative Surface Analysis (4.2.6.4.3 D) (non-destructive) 5 devices 5 devices

Thermal Testing Level B Thermal Cycling Test (Appendix C.2) All devices All devices Electrical Testing Level C
Electrical Testing (Appendix C.3) 116 devices All devices Burn-In Level D

Burn-In (Pre & Post) (Appendix C.4) 45 Devices 45 devices or all devices, whichever is less Hermeticity Verification
(Fine and Gross Leak) Level E Hermeticity Verification (Fine and Gross Leak) (Appendix C.5) All devices All devices
Scanning Acoustic Microscopy (SAM) Level F Scanning Acoustic Microscopy (SAM) (Appendix C.6) As specified As
specified Other Level G

Other test/inspections As specified